



P-Channel Enhancement Mode Power MOSFET **MXD10P03K**

DESCRIPTION

The MXD10P03K uses advanced trench technology to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

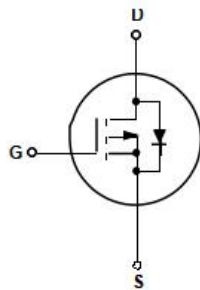
GENERAL FEATURES

- $V_{DS} = -30V$, $I_D = -60A$
 $R_{DS(ON)}(Typ.) = 11m\Omega @ V_{GS} = -4.5V$
 $R_{DS(ON)}(Typ.) = 7.5m\Omega @ V_{GS} = -10V$
- Low Thermal Resistance
- Advanced trench cell design

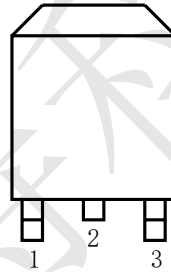
APPLICATION

- Motor drivers
- DC-DC Converter

PINOUT



Schematic diagram



TO-252 top view

Pin	Description
1	Gate(G)
2	Source(S)
3	Drain(D)

ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MXD10P03K	-55°C to 150°C	TO252	2500

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current ($V_{GS} = -10V$) ^(Note1)	I_D	-60	A
Pulsed Source Current ($V_{GS} = -10V$) ^{(Note1)(Note2)(Note3)}	I_{DM}	-144	A
Diode Forward Current	I_S	-60	A
Total Power Dissipation ^(Note1)	P_{tot}	20	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C
Thermal Resistance, Junction-to-Case ^(Note1)	$R_{\theta JC}$	6	°C/W

Note 1. Surface Mounted on 1 in² pad area, $t \leq 10$ sec

Note 2. Pulse width $\leq 10\mu s$, duty cycle $\leq 1\%$

Note 3. limited by bonding wire



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ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-24V, V_{GS}=0V$	-	-	-1	μA
		$V_{DS}=-24V, V_{GS}=0V, T_J=85^\circ C$	-	-	-30	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
On Characteristics						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	-1.5	-2.4	V
Drain-Source On-State Resistance ^(Note1)	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-10A$	-	11	14	m Ω
		$V_{GS}=-10V, I_D=-20A$	-	7.5	9	m Ω
Dynamic Characteristics ^(Note2)						
Input Capacitance	C_{iss}	$V_{DS}=-15V, V_{GS}=0V, F=1.0MHz$	-	2000	-	pF
Output Capacitance	C_{oss}		-	290	-	pF
Reverse Transfer Capacitance	C_{rss}		-	270	-	pF
Switching Characteristics ^(Note2)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=-15V, I_D=-20A, V_{GEN}=-10V, R_G=4.5\Omega, R_L=0.75\Omega,$	-	10	-	nS
Turn-on Rise Time	t_r		-	8	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	43	-	nS
Turn-Off Fall Time	t_f		-	18	-	nS
Total Gate Charge	Q_g	$V_{DS}=-15V, I_{DS}=-20A, V_{GS}=-10V$	-	36	-	nC
Gate-Source Charge	Q_{gs}		-	5.3	-	nC
Gate-Drain Charge	Q_{gd}		-	8.8	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note1)	V_{SD}	$V_{GS}=0V, I_{SD}=-20A$	-	-	-1.3	V
Reverse Recovery Time	t_{rr}	$I_{SD}=-20A, di_{SD}/dt=100A/\mu s$	-	21	-	nS
Reverse Recovery Charge	Q_{rr}		-	14	-	nC

Note 1. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

Note 2. Guaranteed by design, not subject to production testing



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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1. Power Capability

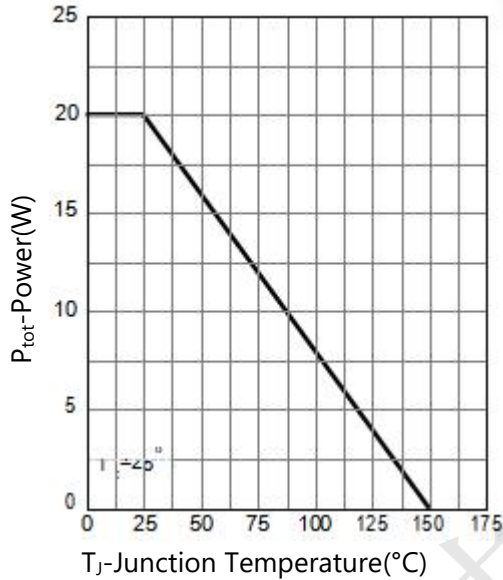


Figure 2. Current Capability

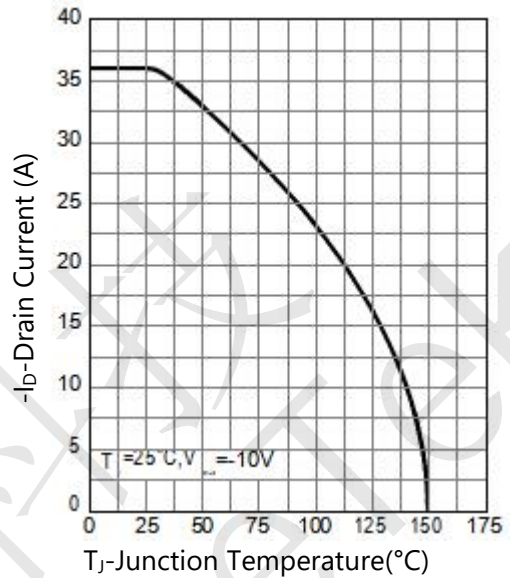


Figure 3. Safe Operation Area

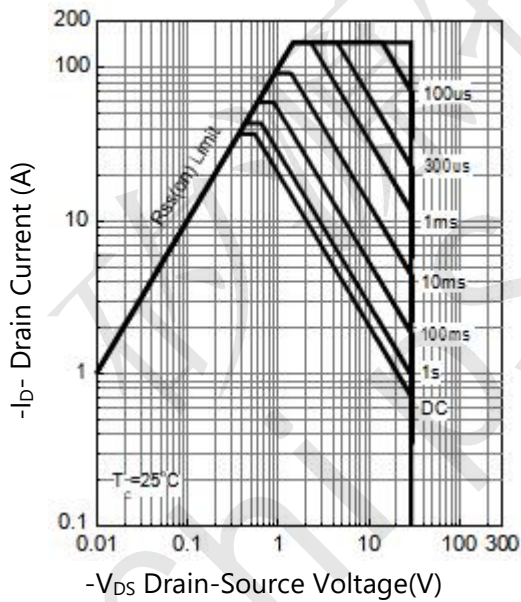
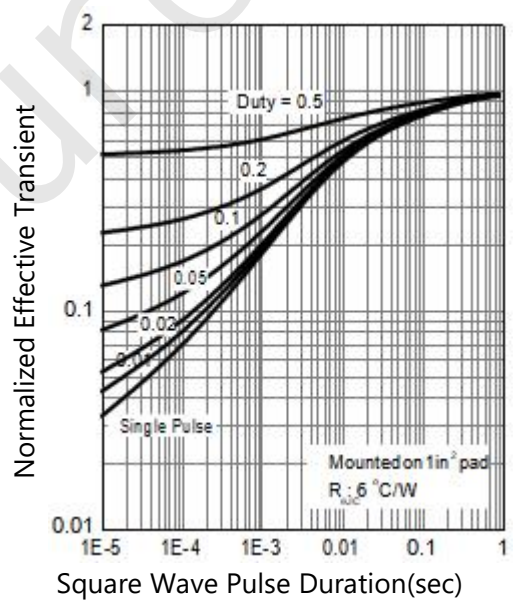


Figure 4. Transient Thermal Impedance





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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 5. Output Characteristics

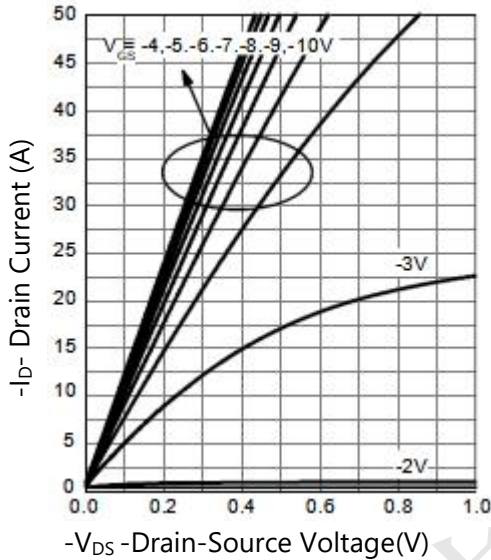


Figure 6. Drain-Source On Resistance

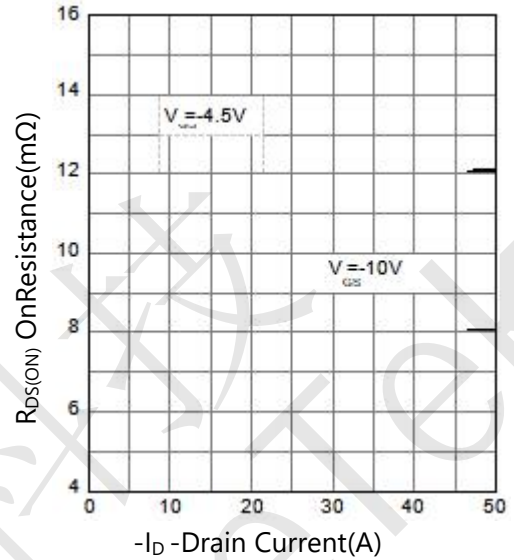


Figure 7. Transfer Characteristics

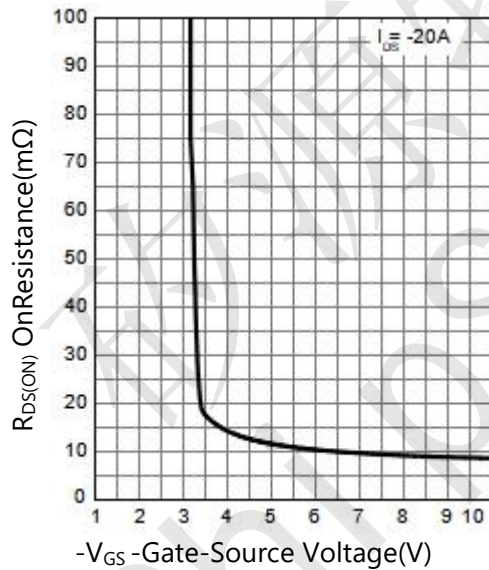
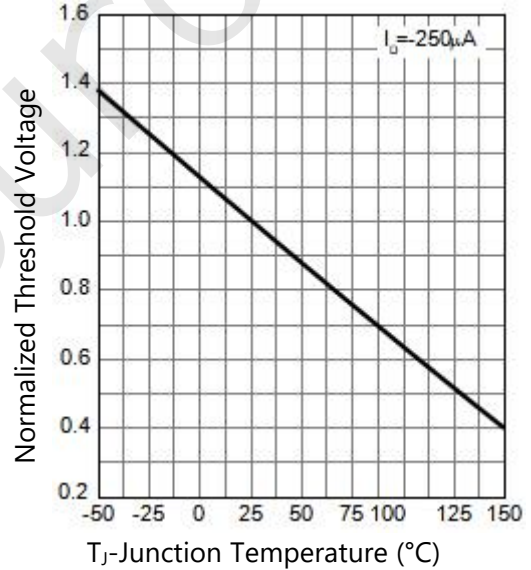


Figure 8. Normalized Threshold Voltage





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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 9. Normalized On Resistance

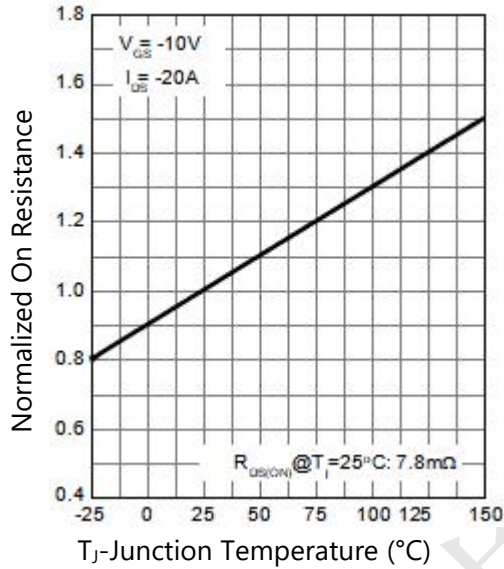


Figure 10. Diode Forward Current

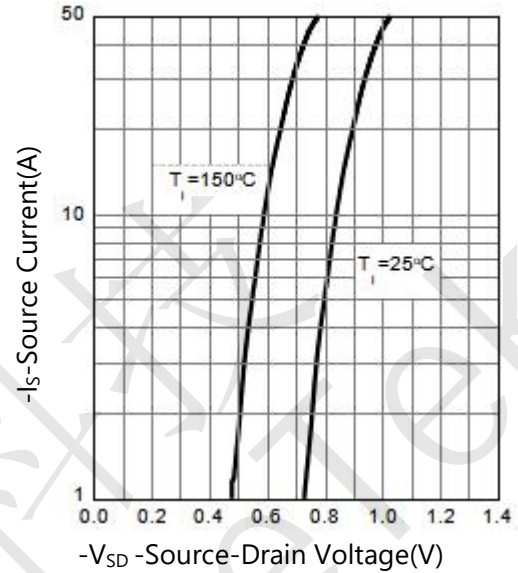


Figure 11. Capacitance

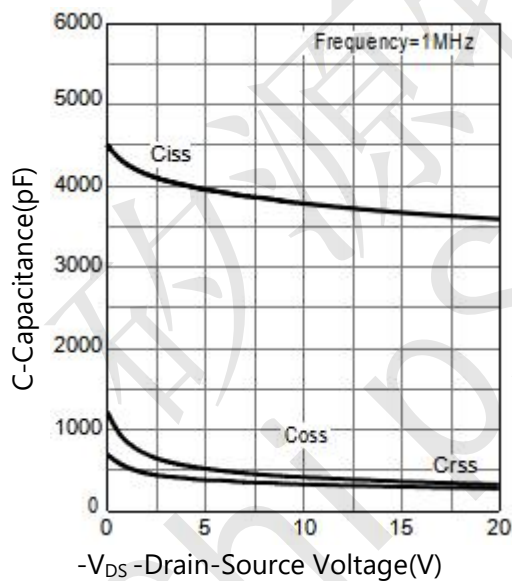
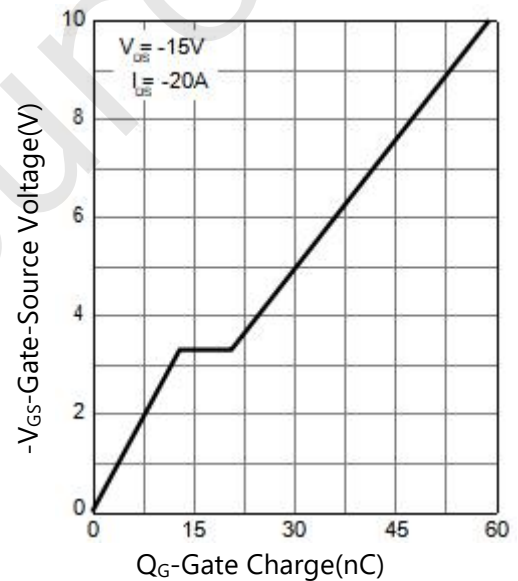


Figure 12. Gate Charge



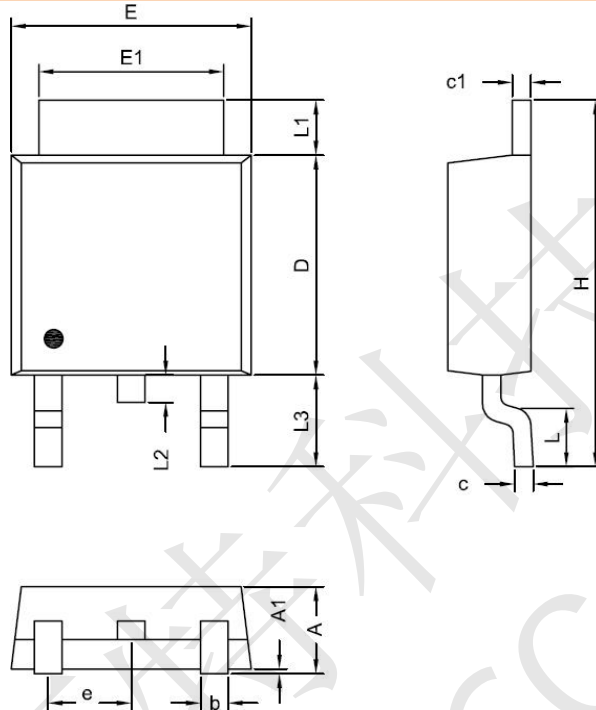


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PACKAGE INFORMATION

TO252



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	2.19	2.38
A1	0.02	0.13
D	5.30	6.40
E	6.35	6.80
E1	5.20	5.50
c	0.40	0.60
C1	0.40	0.60
b	0.55	0.85
e	2.30 BCS	
L	1.00	1.80
L1	0.70	1.80
L2	0.70 BCS	
L3	2.40	2.80
H	9.20	10.40